

ABSTRACT OF THE DISCLOSURE

In a light emitting device, a light emitting element which includes a transparent substrate and a stack of GaN-based compound semiconductor layers formed on the first surface of the transparent substrate is mounted on a lead frame or a printed circuit board so that the transparent substrate is located on the side of the stack of GaN-based compound semiconductor layers opposite to the lead frame or the printed circuit board. The second surface of the transparent substrate opposite to the first surface contains a portion inclined with respect to the first surface. Alternatively, an optical member is arranged in contact with the second surface of the transparent substrate, where a surface of the optical member located on the opposite side to the transparent substrate contains a portion inclined with respect to the first surface of the transparent substrate.